

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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# HD74HC620/HD74HC623

Octal Bus Transceivers (with inverted 3-state outputs)  
Octal Bus Transceivers (with 3-state outputs)



ADE-205-516 (Z)  
1st. Edition  
Sep. 2000

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## Description

This octal bus transceiver is designed for asynchronous two-way communication between data buses. The control function implementation allows for maximum flexibility in timing.

This device allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the enable inputs ( $\overline{\text{GBA}}$  and GAB).

The enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives these devices the capability to store data by simultaneous enabling of  $\overline{\text{GBA}}$  and GAB. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 in all) will remain at their last states. The 8-bit codes appearing on the two sets of buses will be identical for the HD74HC623 or complementary for the HD74HC620.

## Features

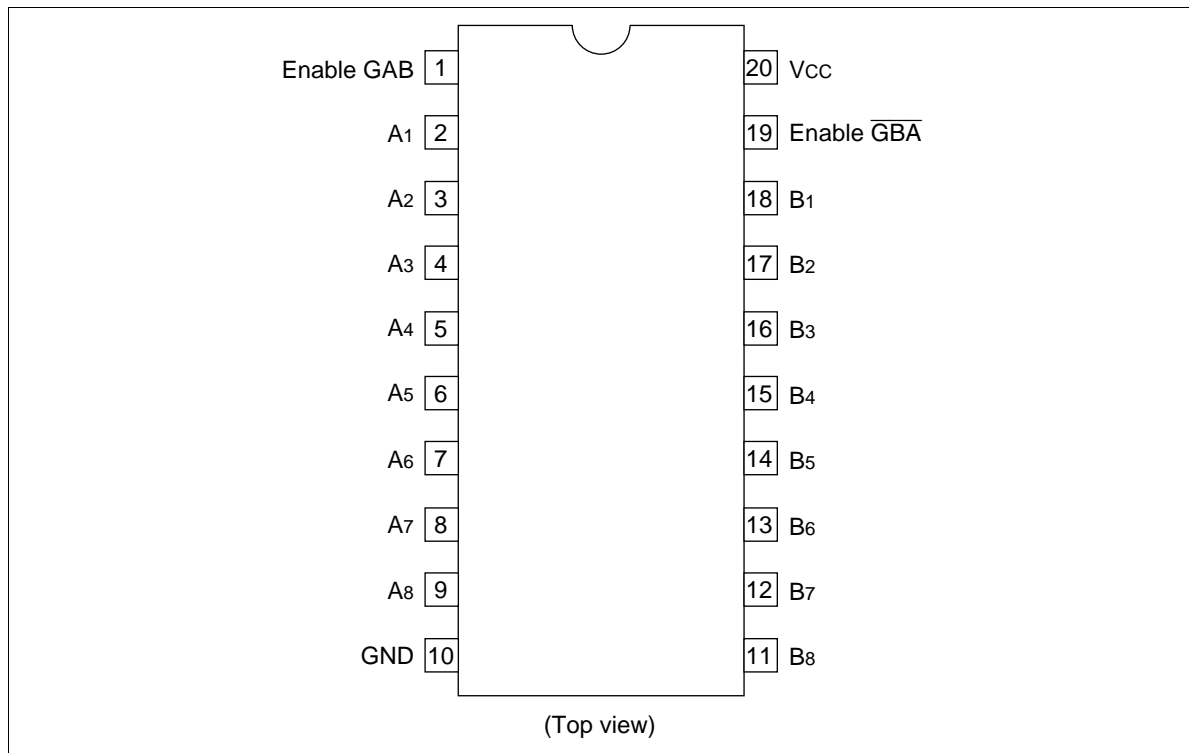
- High Speed Operation:  $t_{pd}$  (Bus to Bus) = 12 ns typ ( $C_L = 50$  pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage:  $V_{CC} = 2$  to 6 V
- Low Input Current: 1  $\mu\text{A}$  max
- Low Quiescent Supply Current:  $I_{CC}$  (static) = 4  $\mu\text{A}$  max ( $T_a = 25^\circ\text{C}$ )

# HD74HC620/HD74HC623

## Function Table

Enable Inputs		Operation	
$\overline{\text{GBA}}$	GAB	HD74HC620	HD74HC623
L	L	$\overline{\text{B}}$ data to A bus	B data to A bus
H	H	$\overline{\text{A}}$ data to B bus	A data to B bus
H	L	Isolation	Isolation
L	H	$\overline{\text{B}}$ data to A bus, $\overline{\text{A}}$ data to B bus	B data to A bus, A data to B bus

Pin Arrangement



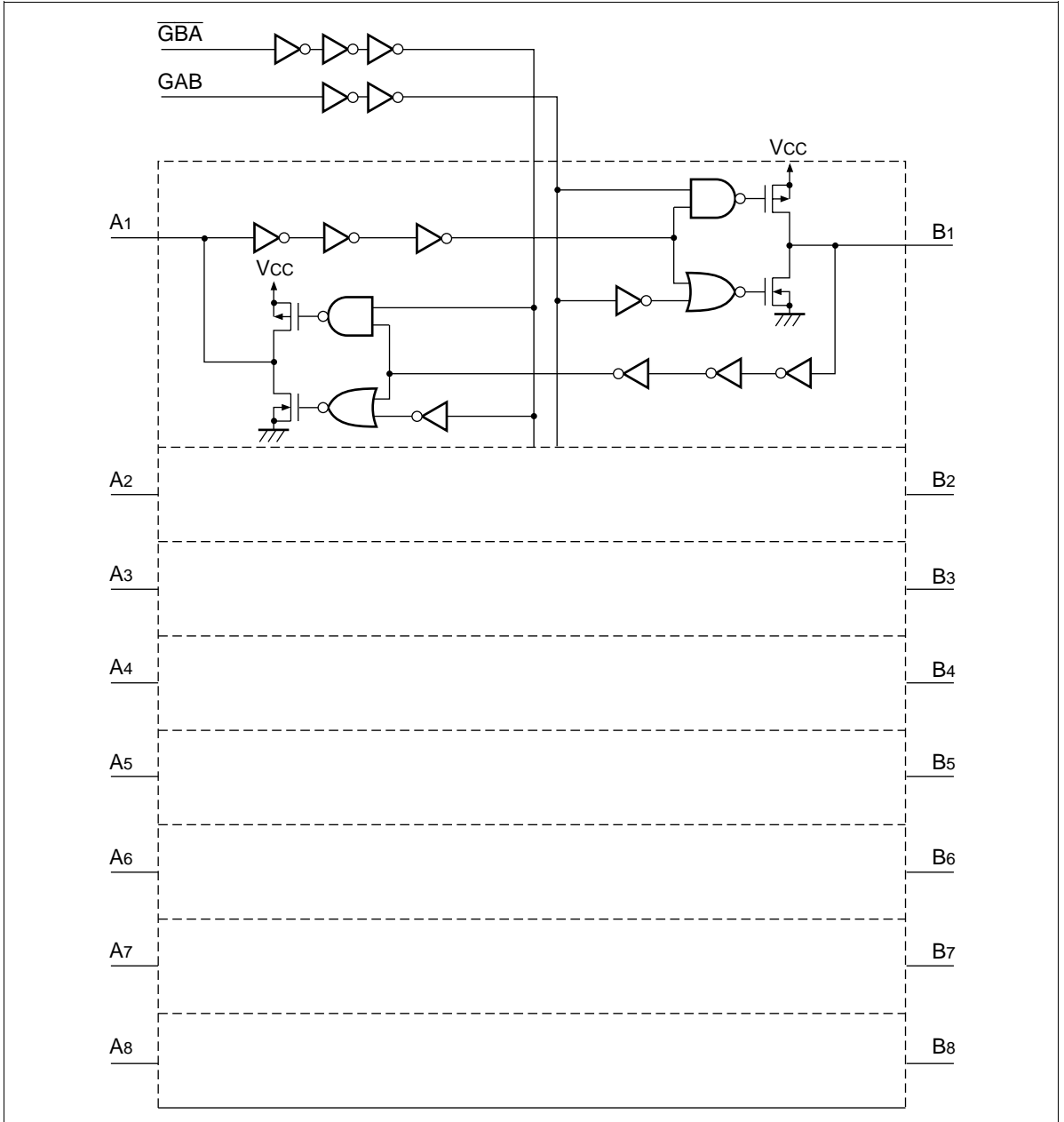
Absolute Maximum Ratings

Item	Symbol	Rating	Unit
Supply voltage range	$V_{CC}$	-0.5 to +7.0	V
Input voltage	$V_{IN}$	-0.5 to $V_{CC} + 0.5$	V
Output voltage	$V_{OUT}$	-0.5 to $V_{CC} + 0.5$	V
Output current	$I_{OUT}$	$\pm 35$	mA
DC current drain per $V_{CC}$ GND	$I_{CC}, I_{GND}$	$\pm 75$	mA
DC input diode current	$I_{IK}$	$\pm 20$	mA
DC output diode current	$I_{OK}$	$\pm 20$	mA
Power Dissipation per package	$P_T$	500	mW
Storage temperature	$T_{stg}$	-65 to +150	$^{\circ}C$

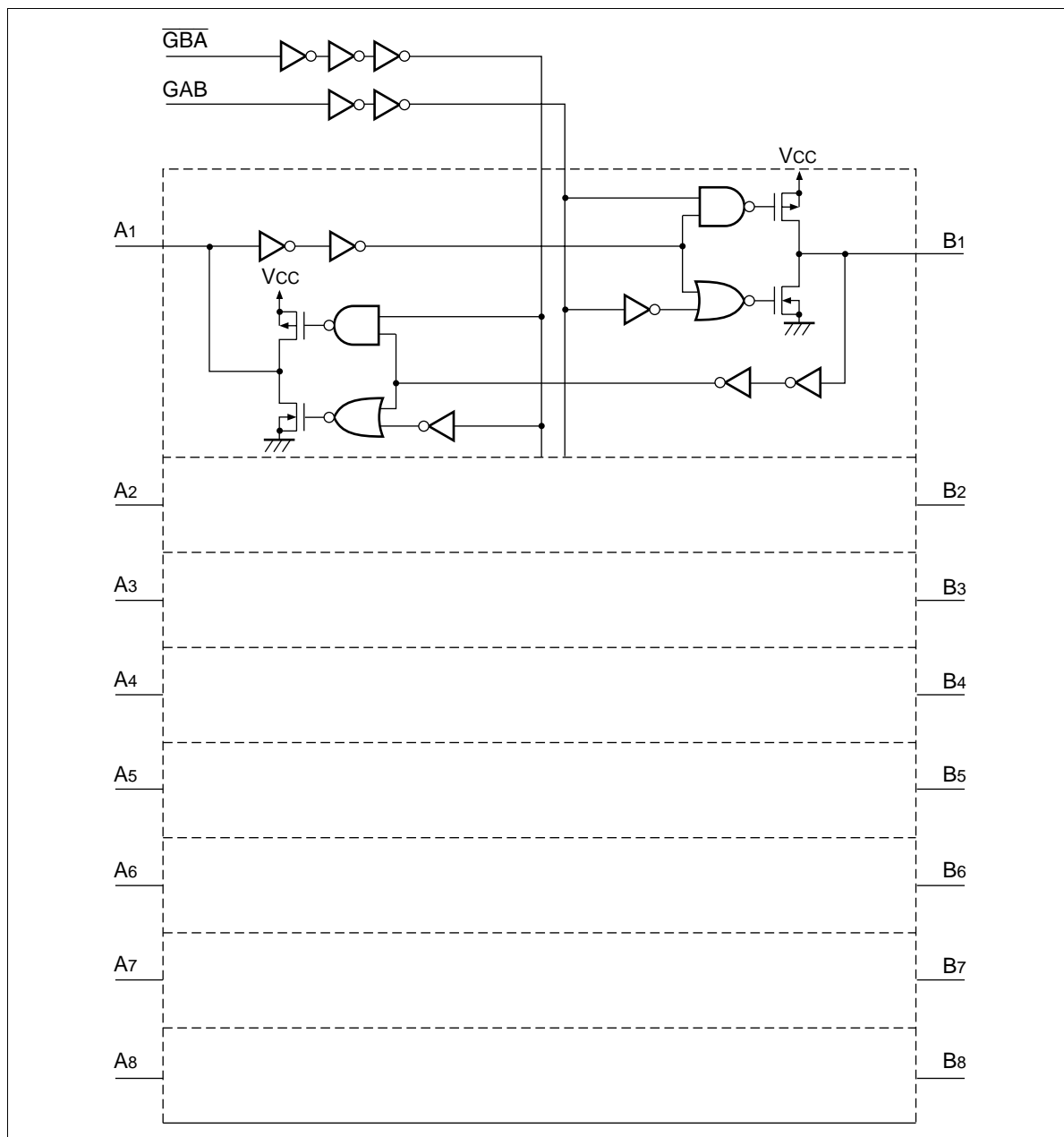
# HD74HC620/HD74HC623

## Block Diagram

### HD74HC620



HD74HC623



## DC Characteristics

Item	Symbol	V <sub>CC</sub> (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V <sub>IH</sub>	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V <sub>IL</sub>	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V <sub>OH</sub>	2.0	1.9	2.0	—	1.9	—	V	Vin = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I <sub>OH</sub> = -6 mA
		6.0	5.68	—	—	5.63	—			I <sub>OH</sub> = -7.8 mA
	V <sub>OL</sub>	2.0	—	0.0	0.1	—	0.1	V	Vin = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I <sub>OL</sub> = 6 mA
		6.0	—	—	0.26	—	0.33			I <sub>OL</sub> = 7.8 mA
Off-state output current	I <sub>OZ</sub>	6.0	—	—	±0.5	—	±5.0	μA	Vin = V <sub>IH</sub> or V <sub>IL</sub> , Vout = V <sub>CC</sub> or GND	
Input current	I <sub>in</sub>	6.0	—	—	±0.1	—	±1.0	μA	Vin = V <sub>CC</sub> or GND	
Quiescent supply current	I <sub>CC</sub>	6.0	—	—	4.0	—	40	μA	Vin = V <sub>CC</sub> or GND, Iout = 0 μA	

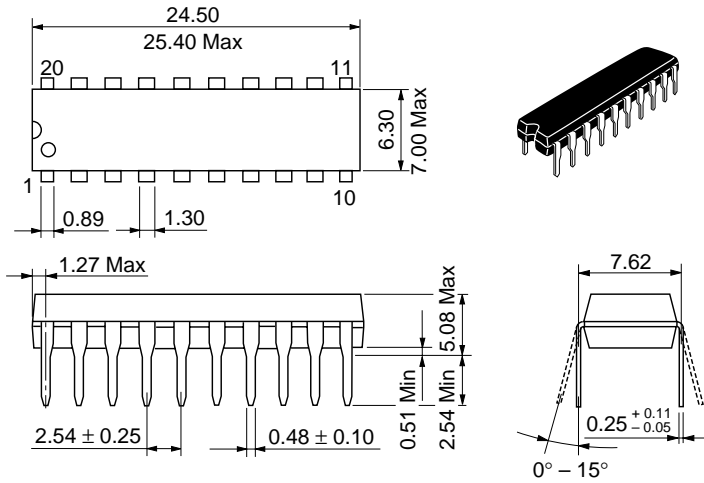


AC Characteristics ( $C_L = 50$  pF, Input  $t_r = t_f = 6$  ns)

Item	Symbol	$V_{CC}$ (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Propagation delay time	$t_{PLH}$	2.0	—	—	100	—	125	ns	
	$t_{PHL}$	4.5	—	12	20	—	25		
		6.0	—	—	17	—	21		
Output enable time	$t_{ZH}$	2.0	—	—	150	—	190	ns	
	$t_{ZL}$	4.5	—	12	30	—	38		
		6.0	—	—	26	—	33		
Output disable time	$t_{HZ}$	2.0	—	—	150	—	190	ns	
	$t_{LZ}$	4.5	—	16	30	—	38		
		6.0	—	—	26	—	33		
Output rise/fall time	$t_{TLH}$	2.0	—	—	60	—	75	ns	
	$t_{THL}$	4.5	—	4	12	—	15		
		6.0	—	—	10	—	13		
Input capacitance	$C_{in}$	—	—	5	10	—	10	pF	

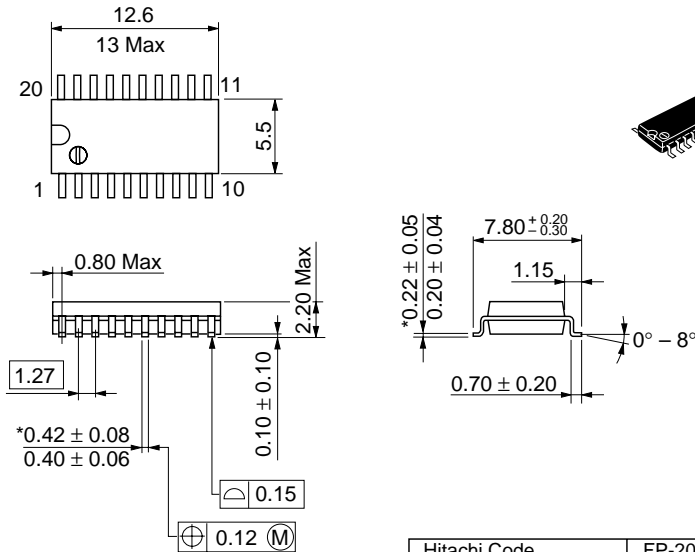
## Package Dimensions

Unit: mm



Hitachi Code	DP-20N
JEDEC	—
EIAJ	Conforms
Mass (reference value)	1.26 g

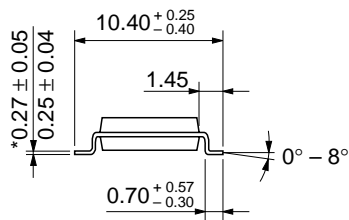
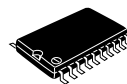
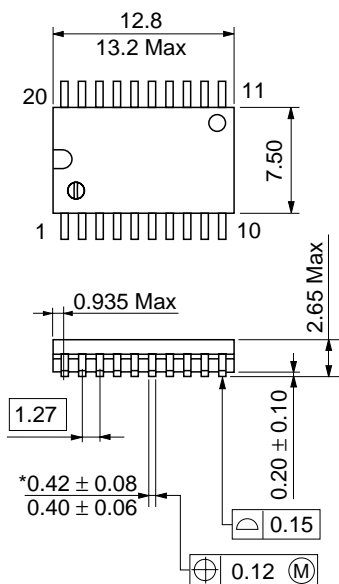
Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	FP-20DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.31 g

Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	FP-20DB
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.52 g

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